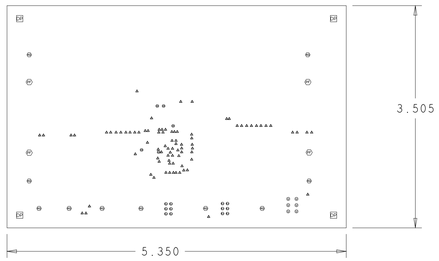
REVISION:H00			
REV	DESCRIPTION	DATE	APPROVED
X	INITIAL RELEASE	ddMMMyy	X



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY	NOTES
A	12.0	+3.0/-10.0	PLATED	84	
AA	20.0	+3.0/-3.0	PLATED	5	
U	35.43	+3.0/-3.0	PLATED	6	
CJ	40.0	+3.0/-3.0	PLATED	12	
AG	100.0	+3.0/-3.0	PLATED	10	
AY	213.0	+3.0/-3.0	PLATED	4	
DB	187.01	+3.0/-3.0	NON-PLATED	4	

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ANALOG DEVICES

TITLE

FABRICATION

EVAL-ADPL74101-AZ

APPROVAL	DATE
DESIGNER CCORREA	10OCT25
ENGINEER LONOFREL	10OCT25
APPROVAL X	ddMMMyy

DO NOT SCALE DWG

SIZE D

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES

TOLERANCES
DECIMAL: .XX±0.005 .XXX±0.010 .XXXX±0.005
ANGLES ±0°
ANG: .X ±0.5°
.XX ±0.25°
.XXX ±0.050

DRAWING NUMBER 09-100205

REV B

SCALE 1/1

TEMPLATE REV:

SHEET 1 OF 2

CUSTOMER_EVALUATION_TEMPLATE

REVISION=H00			
REV	DESCRIPTION	DATE	APPROVED
X	INITIAL RELEASE	ddMMMyy	X

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
   ALL DOCUMENTS & SPECIFICATIONS REFERRED TO BELOW SHOULD BE THE LATEST REVISIONS.

MATERIAL: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLAINT WITH THE EU DIRECTIVE 2002/95/EC

2. BOARD MATERIAL:(USE CHECKED ITEMS)
   (X) ISOLA 370HR OR S1000-2 OR IT180 OR EQUIVALENT
   ( ) ISOLA-FR408HR OR EQUIVALENT
   ( ) ISOLA IS410
   ( ) MEGTRON 6
   ( ) NELCO-4000-13
   ( ) ROGERS 4350B
   ( ) ROGERS 3003
   ( ) ARLON 85N
   ( ) EM370D
   ( ) OTHER _____

3. ALL LAMINATES & BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103,(TG>170 DEGC TD>300 DEGC)
   UL FLAMMABILITY RATING 94V-0. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796/UL796F.

4. REFER TO IPC-6010 SERIES, CLASS 2 FOR FABRICATION.WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2.

5. REFER TO LAMINATION DIAGRAM FOR OVERALL BOARD THICKNESS, TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING
   PROCESSES. FINISHED THICKNESS MEASURED FROM TOP COPPER TO BOTTOM COPPER.

6. BOW & TWIST NOT TO EXCEED 0.0075 INCHES (0.75%) PER LINEAR INCH AND SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.

7. ACCEPTABILITY PER ADI SPECIFICATION TST00115.

TOOLING:

8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC
   THICKNESS & TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, THE VENDOR MUST
   MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENT MADE TO THE DEFINED STACKUP,
   TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM ADI.

9. FILLET OPTIONS TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS.
   ( ) FILLETS ALLOWED
   (X) FILLETS NOT ALLOWED

10. THIEVING:
    ( ) VENDOR MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS MAINTAINING A MINIMUM
        0.100 INCH CLEARANCE FROM ALL COPPER FEATURES.
    ( ) VENDOR MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS.

11. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003 INCHES.

FINISH:

12. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN 0.005 INCHES DTP,UNLESS SPECIFIED.
    MINIMUM BARREL PLATING OF 0.001 INCHES. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO
    HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED IN UNFILLED VIA IN PAD HOLES.

13. PLATING SPECIFICATION:
    (X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIRMENTS
        THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER
        WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE.

14. SURFACE FINISH:
    (X) IMMERSION GOLD (ENIG) 1.58-3.94 MICRO INCHES OVER 118-236 MICRO INCHES MIN. OF ELECTROLESS NICKEL PER IPC-4552
    ( ) OSP (ORGANIC SOLDERABILITY PRESERVATIVE)
    ( ) IMMERSION SILVER
    ( ) SOFT WIRE BONDABLE GOLD 30-50 MICRO INCHES OF SOFT WIRE
        BONDABLE GOLD OVER 100-150 MICRO INCHES OF NICKEL
    ( ) EDGE CONNECTOR FINGERS ARE TO BE PLATED WITH 100 MICRO-INCHES(.0001") OF LOW STRESS
        NICKEL UNDER 30 MICRO-INCHES (.00003") OF GOLD
    ( ) OTHER_____

15. SOLDERMASK:
    SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) TO MEET IPC-SM-840.
    IF PRESENT,DO NOT MODIFY SOLDERMASK DEFINED PADS (MASK OPENINGS LESS THAN COPPER PAD) WITHOUT APPROVAL.
    (X) LPI
    ( ) OTHER_____

    COLOR
    ( ) GREEN
    (X) OTHER: BLUE

16. APPLY SILKSCREEN TO BOTH SIDES USING A NON-CONDUCTIVE, EPOXY BASED INK PER ARTWORK.
    (X) WHITE
    ( ) OTHER

TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.
    THE PCB SHALL HAVE A VERIFICATION STAMP.

18. A TIME DOMAIN REFLECTOMETER REPORT (TDR) FOR EACH IMPEDANCE CONTROLLED LAYER & A CERTIFICATE
    OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING
    CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES
    IS ACCEPTABLE, ALL OTHER INSTANCES MUST BE REPORTED.

MISCELLANEOUS:

19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN
    USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED
    WITH NON-CONDUCTIVE EPOXY.

20. FOR VIA FILL INFORMATION REFER TO DRILL CHART:
    ( ) NON-CONDUCTIVE EPOXY FILL ALL 0.XXXX INCHES DRILLED VIAS
    ( ) COPPER FILL ALL 0.XXXX INCHES DRILLED VIAS

21. INTENTIONAL SHORTS:
    IF AN INTENTIONAL SHORT REPORT IS SUPPLIED AND DOES NOT MATCH THE FAB DATA THEN
    ADI APPROVAL IS REQUIRED.

22. PEMNUTS:
    ( ) PEMNUTS TO BE INSTALLED BY FABRICATOR
    ( ) PEMNUTS NOT TO BE INSTALLED BY FABRICATOR
    ( ) NOT APPLICABLE

23. MANUFACTURER TO ETCH/STAMP WITH PERMANENT NON-CONDUCTIVE INK
    ON SECONDARY SIDE UNLESS OTHERWISE SPECIFIED:
    A. UL CODE-FLAMMABILITY RATING FOR THOSE APPROVED MATERIALS(IF APPLICABLE)
    B. DATE CODE
    C. LOT NUMBER
    D. MANUFACTURER LOGO

25. PANELIZATION:
    BOARDS TO BE SHIPPED IN ARRAY AND KEPT INTACT
    PANEL TO BE SUBJECTED TO CUSTOMERS APPROVAL
    PANEL SOLDER PASTE STENCIL GERBER TO BE PROVIDED TO ANALOG

27. MINIMUM DESIGN LINE WIDTH IS .008 INCH.
28. MINIMUM DESIGN LINE SPACING IS .008 INCH.

FAB NOTES REVISION: NOVEMBER 21 2022

LAMINATION DIAGRAM

LAYER NUMBER	LAYER NAME	COPPER THICKNESS (OZ,INCH)	DIELECTRIC THICKNESS (INCH)	MATERIALS
1	TOP	2 OZ, 0.0028"		FINAL CU (THICKNESS AFTER PLATING)
			0.006	ISOLA 370HR/EQUIVALENT
2	INTERNAL2	2 OZ, 0.0028"		CU CLAD
			0.01	ISOLA 370HR/EQUIVALENT
3	INTERNAL3	2 OZ, 0.0028"		CU CLAD
			0.014	ISOLA 370HR/EQUIVALENT
4	INTERNAL4	2 OZ, 0.0028"		CU CLAD
			0.01	ISOLA 370HR/EQUIVALENT
5	INTERNAL5	2 OZ, 0.0028"		CU CLAD
			0.006	ISOLA 370HR/EQUIVALENT
6	BOTTOM	2 OZ, 0.0028"		FINAL CU (THICKNESS AFTER PLATING)

THE FINISHED PCB THICKNESS TO BE: 0.062" +/-10%

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EVAL-ADPL74101-AZ

APPROVAL	DATE
DESIGNER CCORREA	10OCT25
ENGINEER LONOFREL	10OCT25
APPROVAL X	ddMMMyy

SIZE: D — UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES DECIMALS ±.XXX FRACTIONS ±1/32 ANGLES ±.XX ±.XXX ±.XXXX ±.XXXX ±.XXXXX

DRAWING NUMBER: 09-100205 — REV: B

DO NOT SCALE DWG — SCALE 1/1 — TEMPLATE REV: — SHEET 2 OF 2